MBR130, NRVB130

Schottky Power Rectifier, Surface Mount

1.0 A, 30 V, SOD-123 Package

This device uses the Schottky Barrier principle with a large area metal—to—silicon power diode. Ideally suited for low voltage, high frequency rectification or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package also provides an easy to work with alternative to leadless 34 package style.

Features

- Guardring for Stress Protection
- Low Forward Voltage
- 125°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- ESD Rating:
 - ♦ Human Body Model = 3
 - ◆ Machine Model = C
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Packages*

Mechanical Characteristics

- Device Marking: S3
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy, Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



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SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES 30 VOLTS



SOD-123 CASE 425 STYLE 1

MARKING DIAGRAM



S3 = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MBR130T1G,	SOD-123	3,000 /
NRVB130T1G	(Pb-Free)	Tape & Reel **
MBR130T3G,	SOD-123	10,000 /
NRVB130T3G	(Pb-Free)	Tape & Reel ***

^{** 8} mm Tape, 7" Reel

^{*** 8} mm Tape, 13" Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MBR130, NRVB130

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	30	V
Average Rectified Forward Current (Rated V _R) T _L = 65°C	I _{F(AV)}	1.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz)	I _{FSM}	5.5	Α
Storage Temperature Range	T _{stg}	-65 to +125	°C
Operating Junction Temperature	TJ	-65 to +125	°C
Voltage Rate of Change (Rated V _R)	dv/dt	1000	V/µs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	230	°C/W
Thermal Resistance, Junction to Lead (Note 1)	$R_{ heta JL}$	108	°C/W

^{1.} FR-4 or FR-5 = 3.5×1.5 inches using a 1 inch Cu pad.

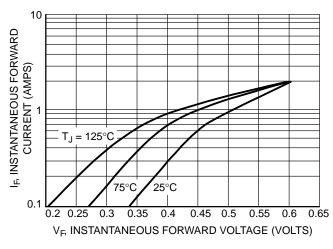
ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Тур	Max	Unit
Instantaneous Forward Voltage (Note 2) $ \begin{array}{l} (I_F=0.1 \text{ A, } T_J=25^\circ\text{C}) \\ (I_F=0.7 \text{ A, } T_J=25^\circ\text{C}) \\ (I_F=1.0 \text{ A, } T_J=25^\circ\text{C}) \end{array} $	V _F	- - 0.47	0.35 0.45 -	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_C = 25^{\circ}C$) ($V_R = 5 \text{ V}, T_C = 25^{\circ}C$)	I _R	60 10		μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{2.} Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2%.

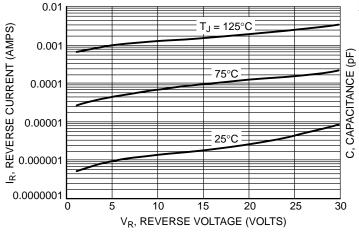
MBR130, NRVB130



0.1 0.2 0.25 0.3 0.35 0.4 0.45 0.5 0.55 0.6 0.65 V_F, INSTANTANEOUS FORWARD VOLTAGE (VOLTS)

Figure 1. Maximum Forward Voltage

Figure 2. Typical Forward Voltage



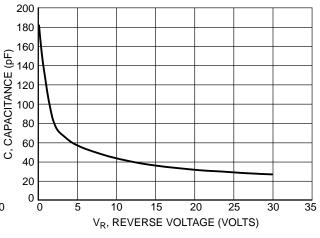
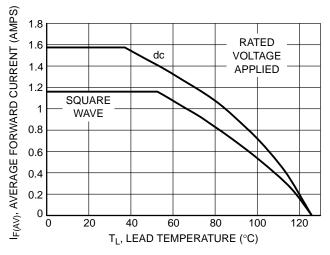


Figure 3. Typical Reverse Current

Figure 4. Typical Capacitance



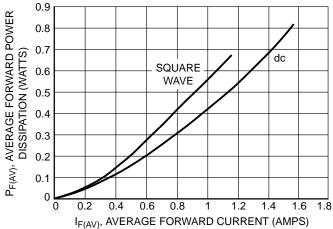


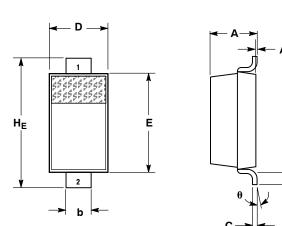
Figure 5. Current Derating, Lead, R_{θJL} = 108°C/W

Figure 6. Forward Power Dissipation

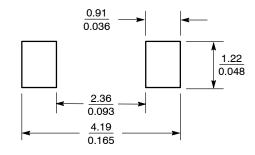


SOD-123 CASE 425-04 ISSUE G

DATE 07 OCT 2009



SOLDERING FOOTPRINT*



SCALE 10:1

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
С			0.15			0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
E	2.54	2.69	2.84	0.100	0.106	0.112
HE	3.56	3.68	3.86	0.140	0.145	0.152
L	0.25			0.010		
θ	0°		10°	0°		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

STYLE 1: PIN 1. CATHODE 2. ANODE

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DESCRIPTION:	SOD-123		PAGE 1 OF 1	

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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